

ABSTRACT OF THE DISCLOSURE

A semiconductor device (1) comprises a semiconductor substrate (2) on which an integrated circuit (3, 4) is formed, a first ground terminal (7) and a second ground terminal (8) for electrically connecting the integrated circuit (3, 4) to an external ground electrode, and an electrostatic breakdown protection element (5) for electrically connecting the first ground terminal (7) with the second ground terminal (8). The first ground terminal (7) is electrically connected with the semiconductor substrate (2), while the second ground terminal (8) is not electrically connected with the semiconductor substrate (2).